

A satellite is shown in space, oriented horizontally. It features a long array of solar panels extending from its central body. Below the main body, a large circular instrument or camera is visible. The background is a vibrant, colorful nebula with shades of purple, pink, and blue, interspersed with numerous stars. The Earth's horizon is visible in the bottom left corner.

Digital Electronics techniques for physics experiments in space

Pisa, 25/07/2017



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- Ingegneria Elettronica a Pisa
- PhD Ingegneria dell'Informazione
 - INFN di Pisa, Upgrade FTK (ATLAS)
 - Elettronica per elaborazione dati dai tracciatori di ATLAS
- IXPE, Missione NASA

Summary

- Attività IXPE
- Esempi di schede Elettroniche
- Criticità in ambienti ostili
- Effetti sull'elettronica delle radiazioni ionizzanti
- Test di irraggiamento
- Conclusioni

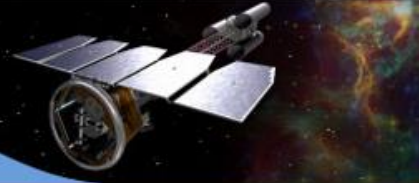


NATIONAL AERONAUTICS
AND SPACE ADMINISTRATION

IXPE

Imaging X-Ray Polarimetry Explorer

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- Missione della NASA per mandare il satellite in orbita nel 2020
- Misurare la polarizzazione dei raggi X provenienti da sorgenti astrofisiche
- Il satellite sarà a circa 500 km di quota
- L'INFN di Pisa ha il compito di progettare e realizzare la Detector Unit del satellite

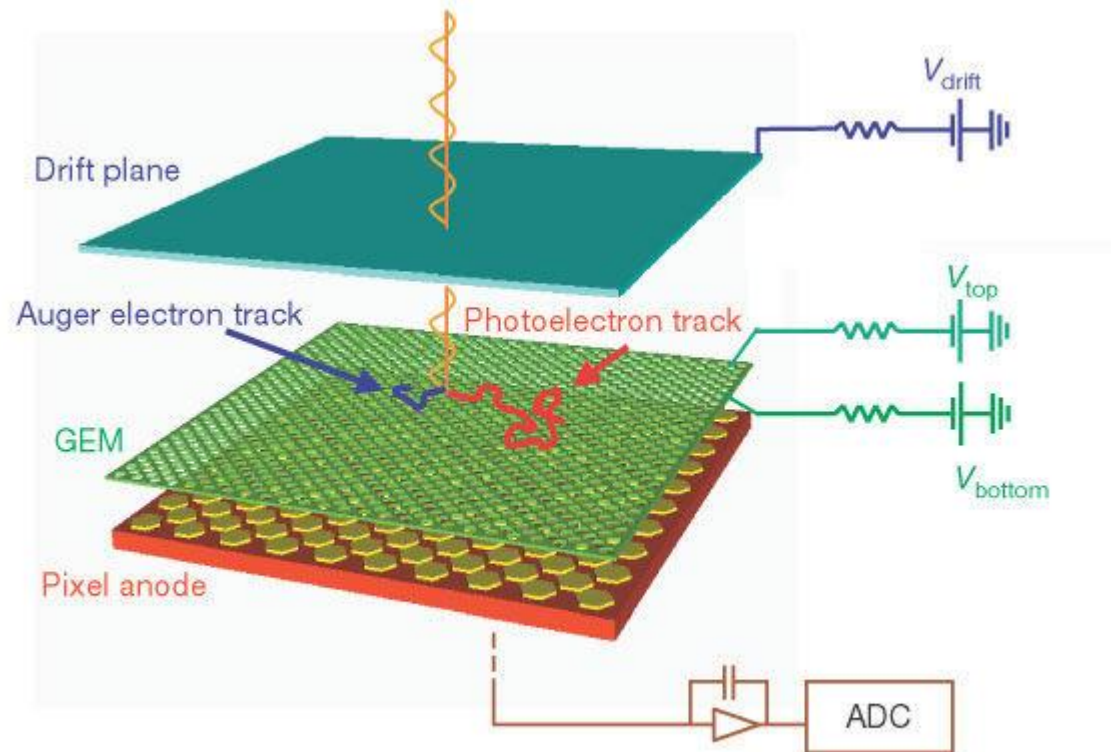
CUBEsat

- Satellite miniaturizzato avente forma cubica
- Volume di 1 dm^3
- Rispetto a missioni «classiche»:
 - Poco costosi
 - Orbite basse
 - Qualifiche meno stringenti
- E' possibile avere cicli di progettazione e produzione rapidi



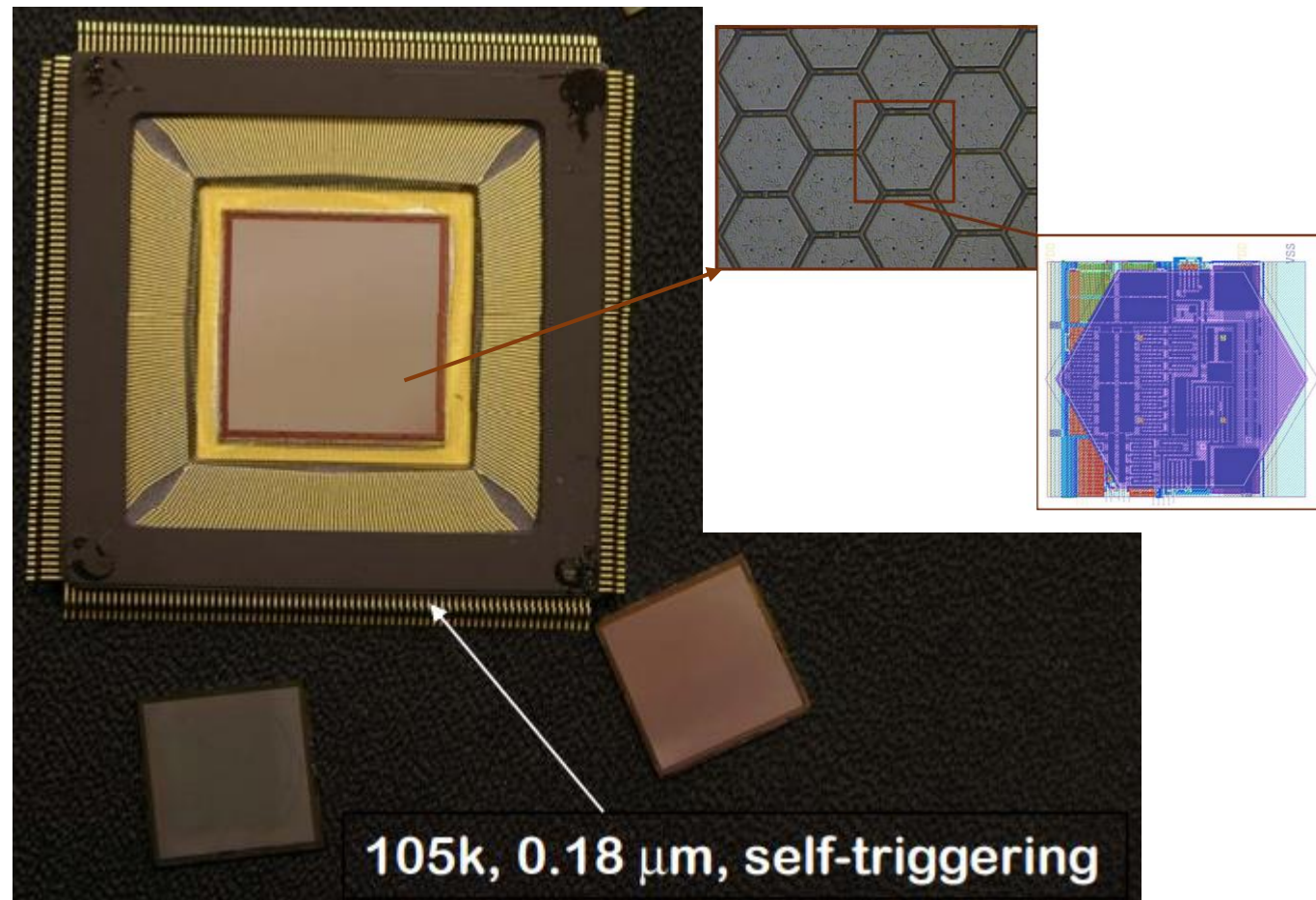
Detector

- Gas Electron Multiplier
- ASIC: XPOL



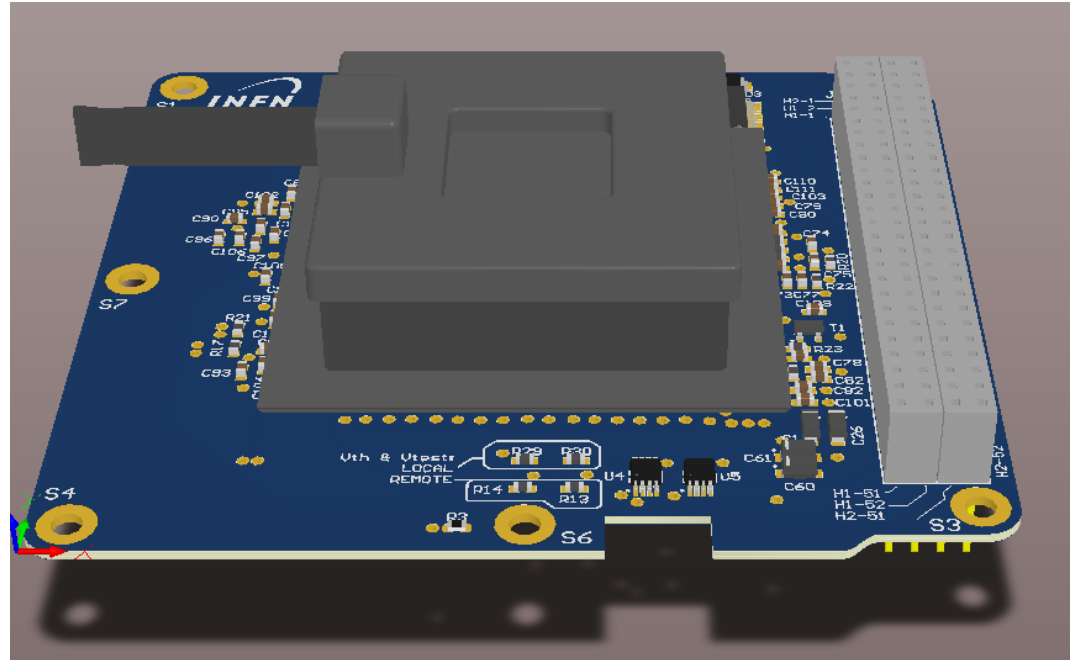
ASIC XPOL

- Gas Electron Multiplier
- ASIC: XPOL
- 105k pixels
- 180nm



Scheda con il Detector

- Detector
- ASIC
- ADC
 - Flash 12 bits
- DACs
 - V threshold
 - V test
- Connector PC 104



Scheda DAQ

- MCU

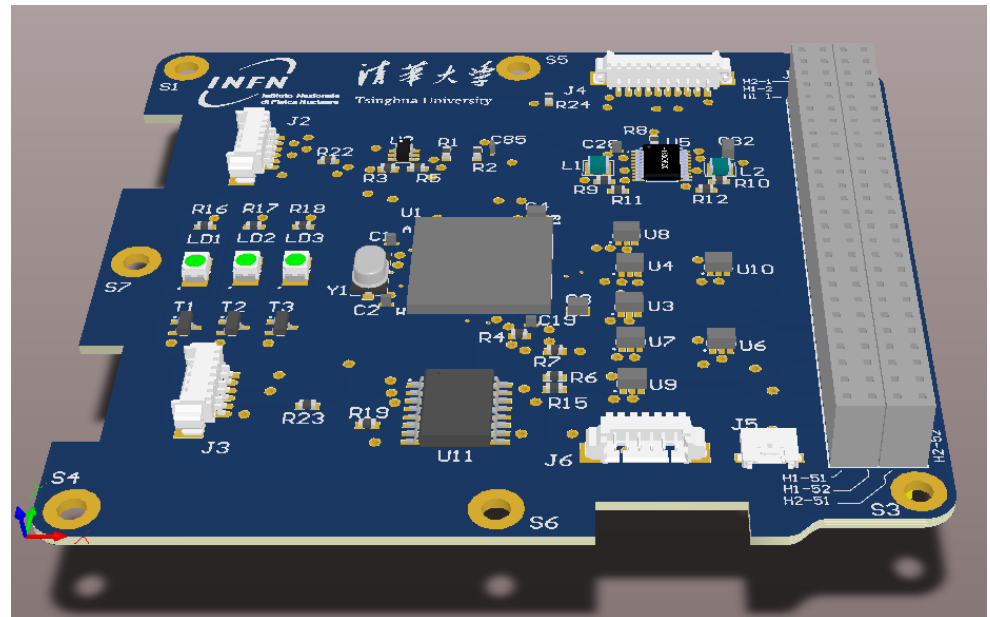
- Texas Instruments TMS570LC4357 Hercules™ Microcontroller Based on the ARM® Cortex®-R Core
- Up to 300MHz
- 125C ambient temperature
- I2C, SPI, CAN, Timers, ADC, ...

- Flash Memory 512 Mb

- Connectors

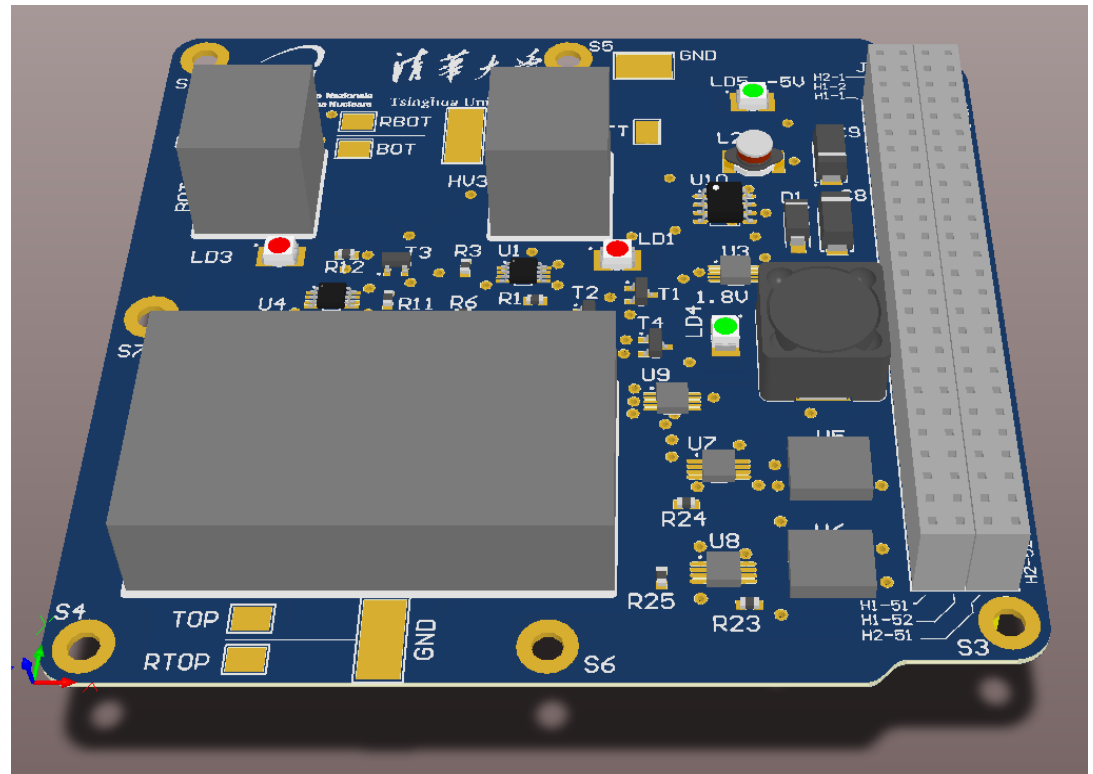
- PC104
- Programmer
- Other Peripherals

- Debug LEDs



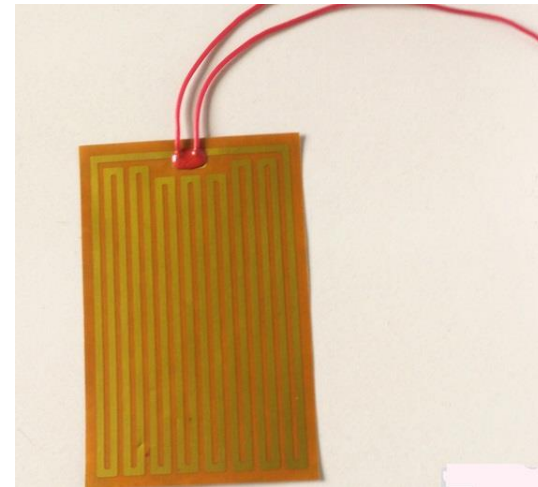
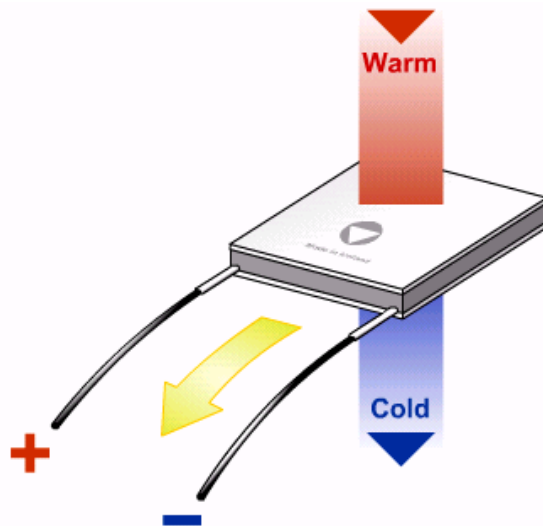
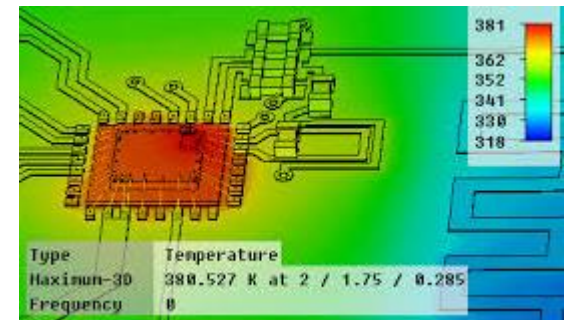
Scheda di Power

- DC-DC Converters:
 - 1.8V
 - -5V
- 3 Channels
- High Voltage
 - Up to -4kV
 - Up to -1kV
 - Up to -1kV
- Latch-up Monitors
- Debug LEDs



Criticità in ambienti ostili

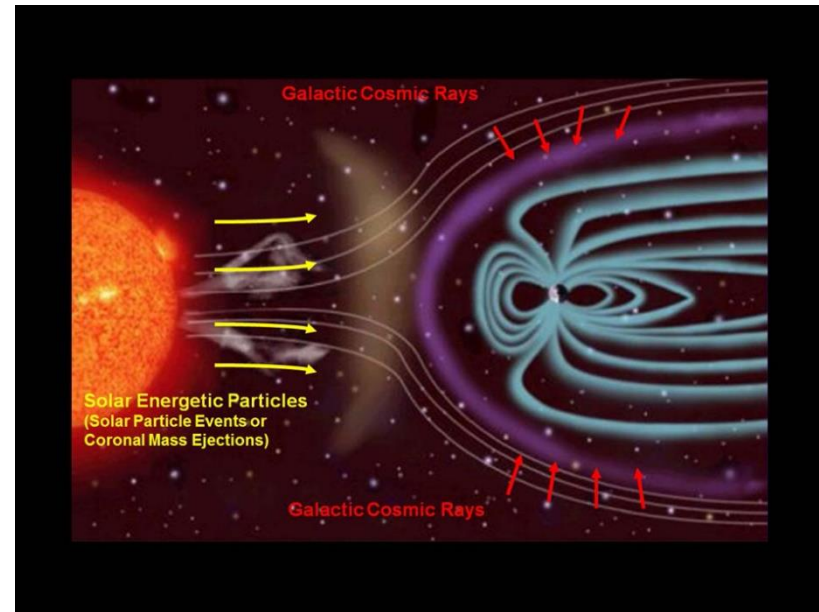
- Presenza di Radiazioni Ionizzanti
- Vuoto: assenza di convezione
 - Controllo della temperature
 - Cicli termici
 - Peltier e Heater e radiatori
 - Componenti std MIL e SP



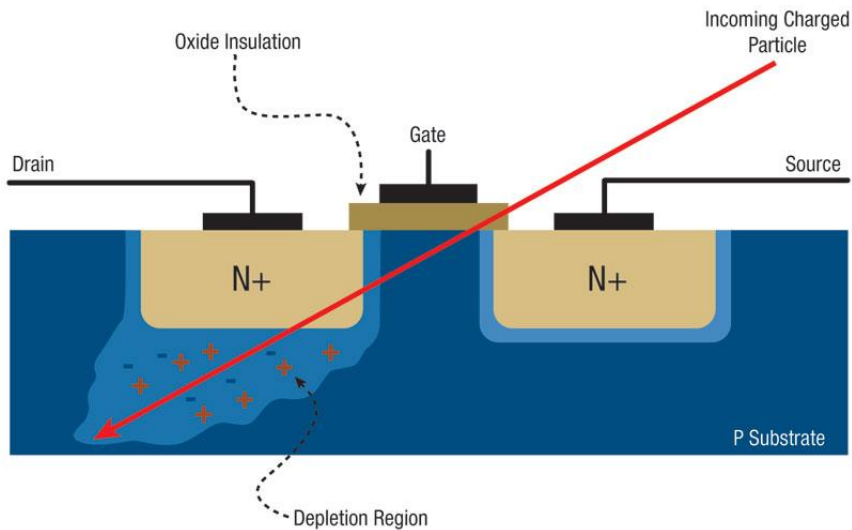
Ionizing Radiation in Space

- **Galactic cosmic radiation** consists of ionized atoms ranging from a single proton up to an uranium nucleus.
- **The Solar wind** contains ions from almost every element in the periodic table; however, it consists primarily of protons and electrons.
- **TRAPPED RADIATION**

The particles are contained in one of two doughnut-shaped magnetic rings surrounding the Earth called the Van Allen radiation belts.



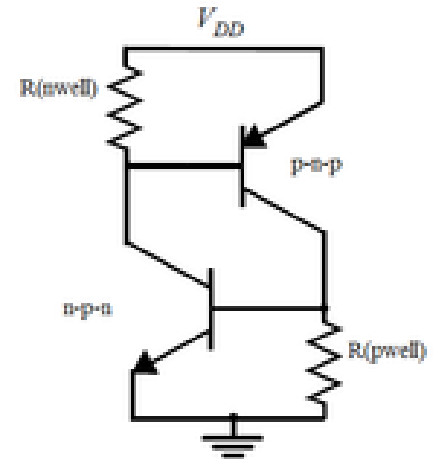
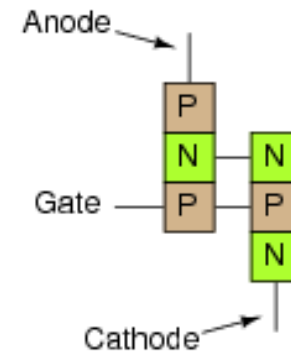
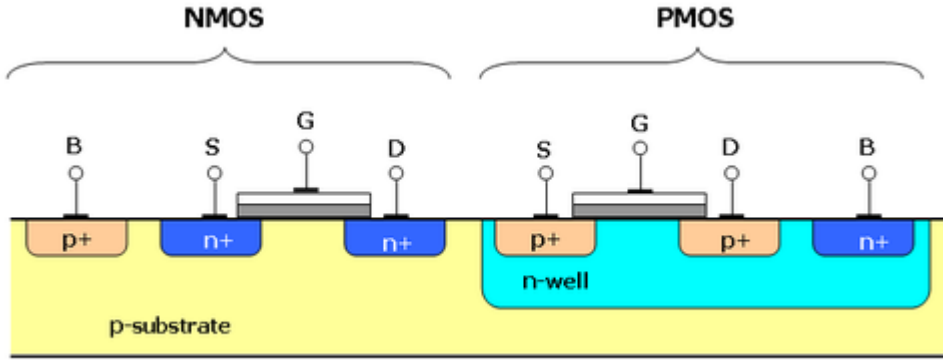
Ionizing Radiation effects on electronic devices



Le cararice generate possono:

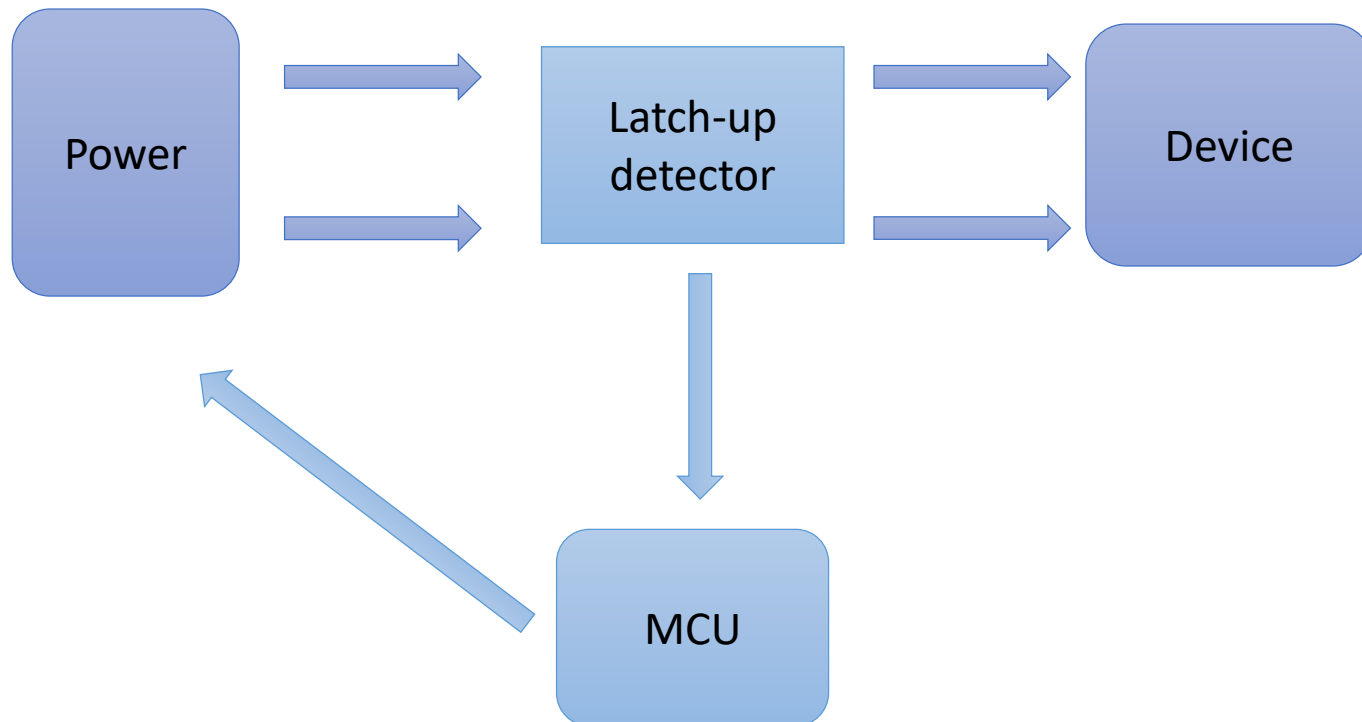
- Far cambiare stato a elementi di memoria “Single Event Upset”
- Innescare fenomeni autodistruttivi. “Single Event Latch-Up”
- Contribuire alla degradazione delle prestazioni. Problema della “Total Dose”

Single Event Latch-Up (SEL)



- ▶ CMOS process
- ▶ SCR parasite
- ▶ Self-sustaining event with a positive feedback
- ▶ If it is not interrupted, it will destroy the ASIC

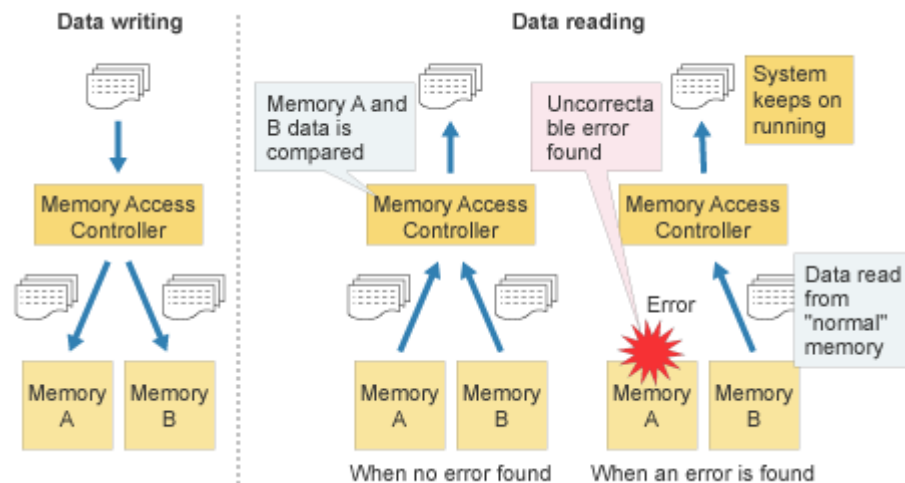
Latch-Up Detector



Single Event Upset (SEU)

- E' un bit flip in un elemento di memoria
 - 1 -> 0 oppure 0 -> 1
- Per proteggersi da questo tipo di problemi:
- Elementi di memoria ridondanti

- Es: 2 memorie che contengono le stesse informazioni



Radiation Test

- Prima di prendere le contromisure
- Capire la suscettibilità del sistema ai SEU e SEL
- Si effettuano test di irraggiamento con ioni pesanti o con raggi X
- Si verificano le funzionalità del sistema sotto test

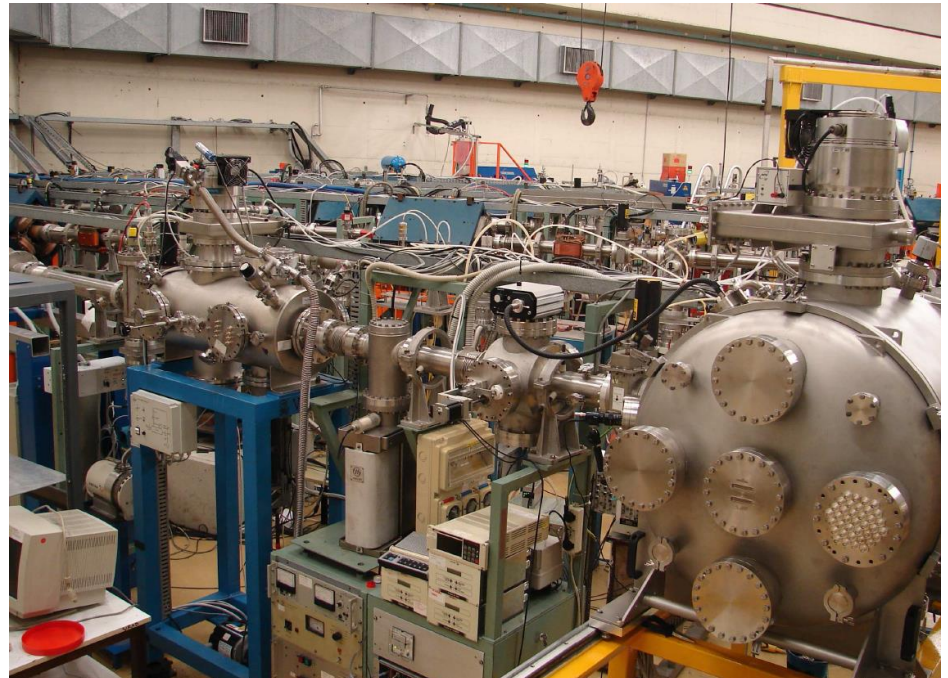
Vi racconto l'esperienza di alcuni test di irraggiamento fatti per l'ASIC XPOL

Radiation Test

- Laboratori Nazionali di Legnaro
- Device under test: XPOL ASIC, CMOS 180nm
- Support qualification process for ESA
 - ESCC Basic Specification No. 25100
- Monitor Single Event Upset (SEU)
- Monitor Single Event Latch-Up (SEL)
- Check the functionality after the total Ionizing dose

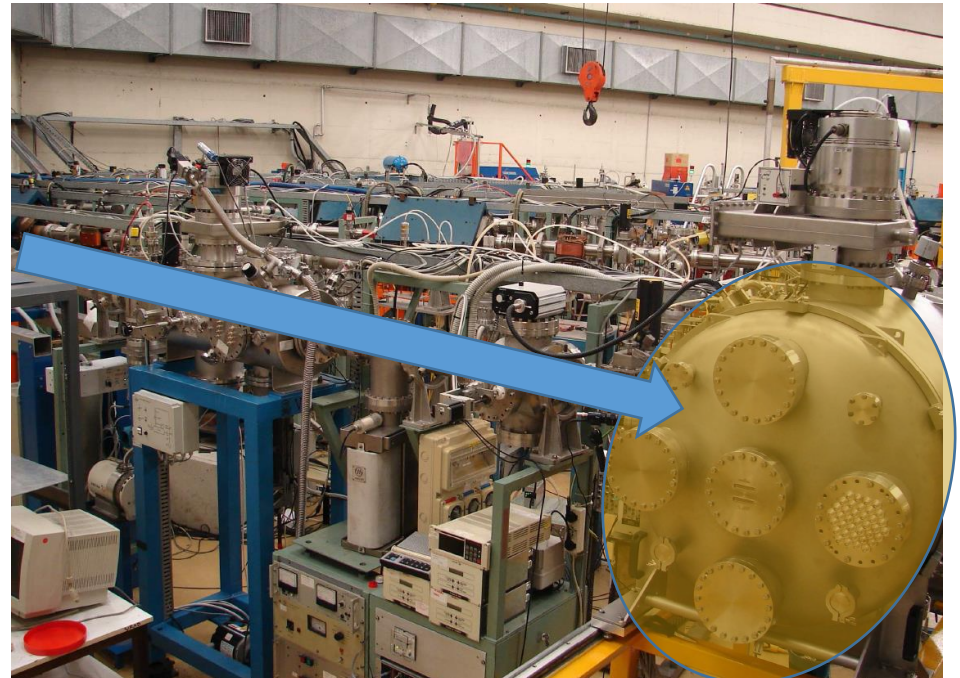
Radiation Test

- SIRAD irradiation facility
- LET :
 - from 0.02 MeV x cm²/mg (¹H)
 - up to 81.7 MeV x cm²/mg (¹⁹⁷Au)
- Flux :
 - 10² - 10⁵ ions/cm²/s
 - irradiation on a 2 X 2 cm² area

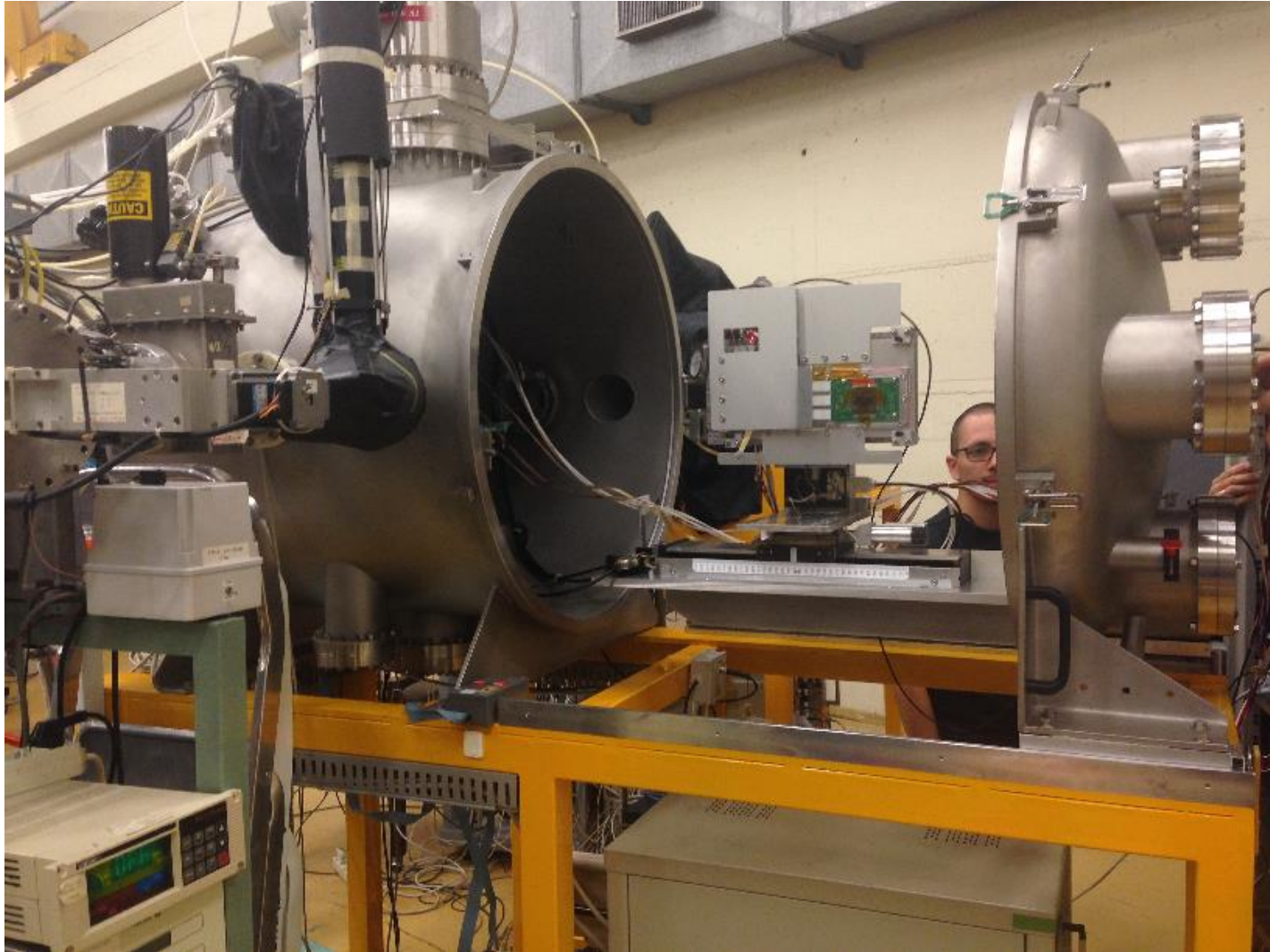


Radiation Test

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Radiation Test



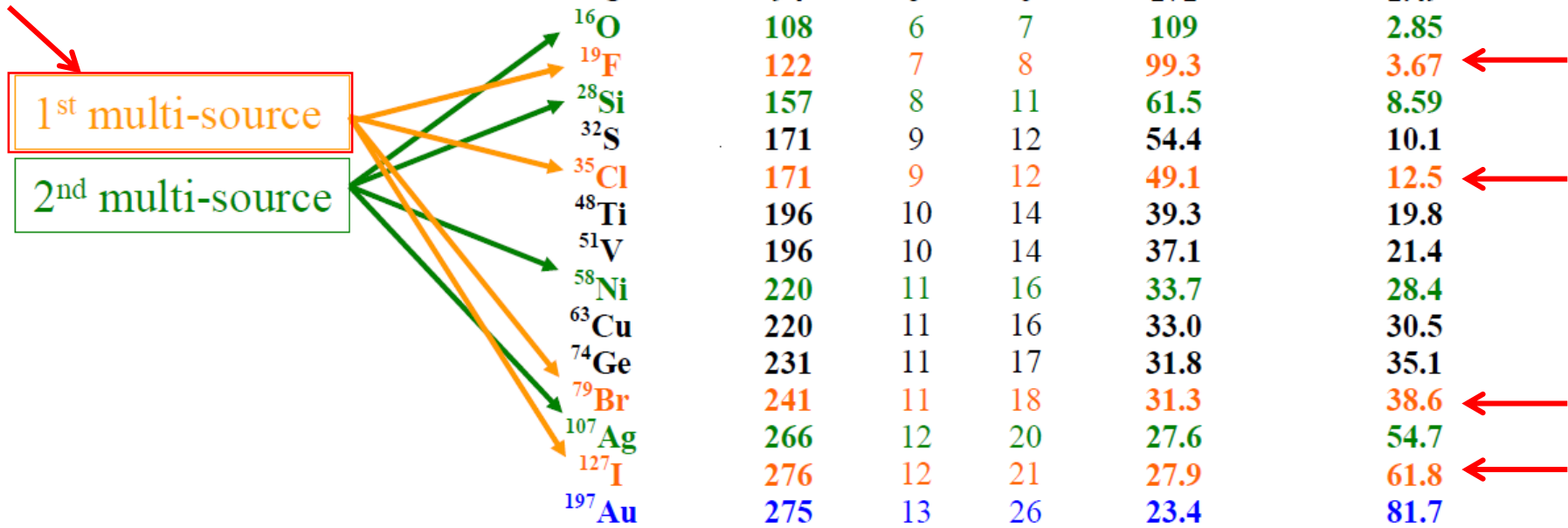
Radiation Test: Ion Species

The energy values refer to the most probable q_1 and q_2 charge state, with two stripper stations, and the Tandem operating at 14 MV.

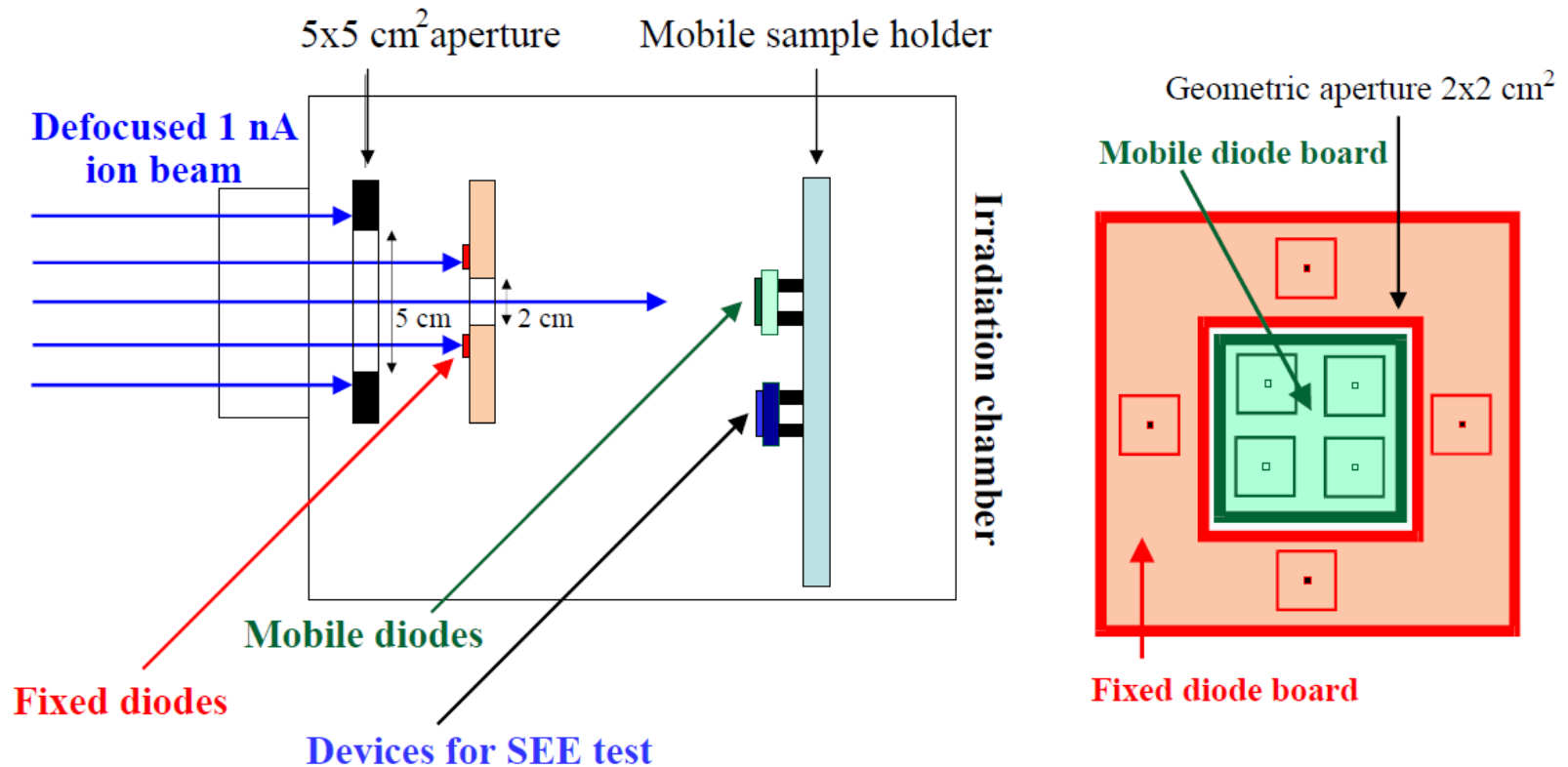
Ion Species	Energy (MeV)	q_1	q_2	Range in Si (μm)	Surface LET in Si ($\text{MeV}\times\text{cm}^2/\text{mg}$)
¹ H	28	1	1	4390	0.02
⁷ Li	56	3	3	378	0.37
¹¹ B	80	4	5	195	1.01
¹² C	94	5	6	171	1.49
¹⁶ O	108	6	7	109	2.85
¹⁹ F	122	7	8	99.3	3.67
²⁸ Si	157	8	11	61.5	8.59
³² S	171	9	12	54.4	10.1
³⁵ Cl	171	9	12	49.1	12.5
⁴⁸ Ti	196	10	14	39.3	19.8
⁵¹ V	196	10	14	37.1	21.4
⁵⁸ Ni	220	11	16	33.7	28.4
⁶³ Cu	220	11	16	33.0	30.5
⁷⁴ Ge	231	11	17	31.8	35.1
⁷⁹ Br	241	11	18	31.3	38.6
¹⁰⁷ Ag	266	12	20	27.6	54.7
¹²⁷ I	276	12	21	27.9	61.8
¹⁹⁷ Au	275	13	26	23.4	81.7

1st multi-source

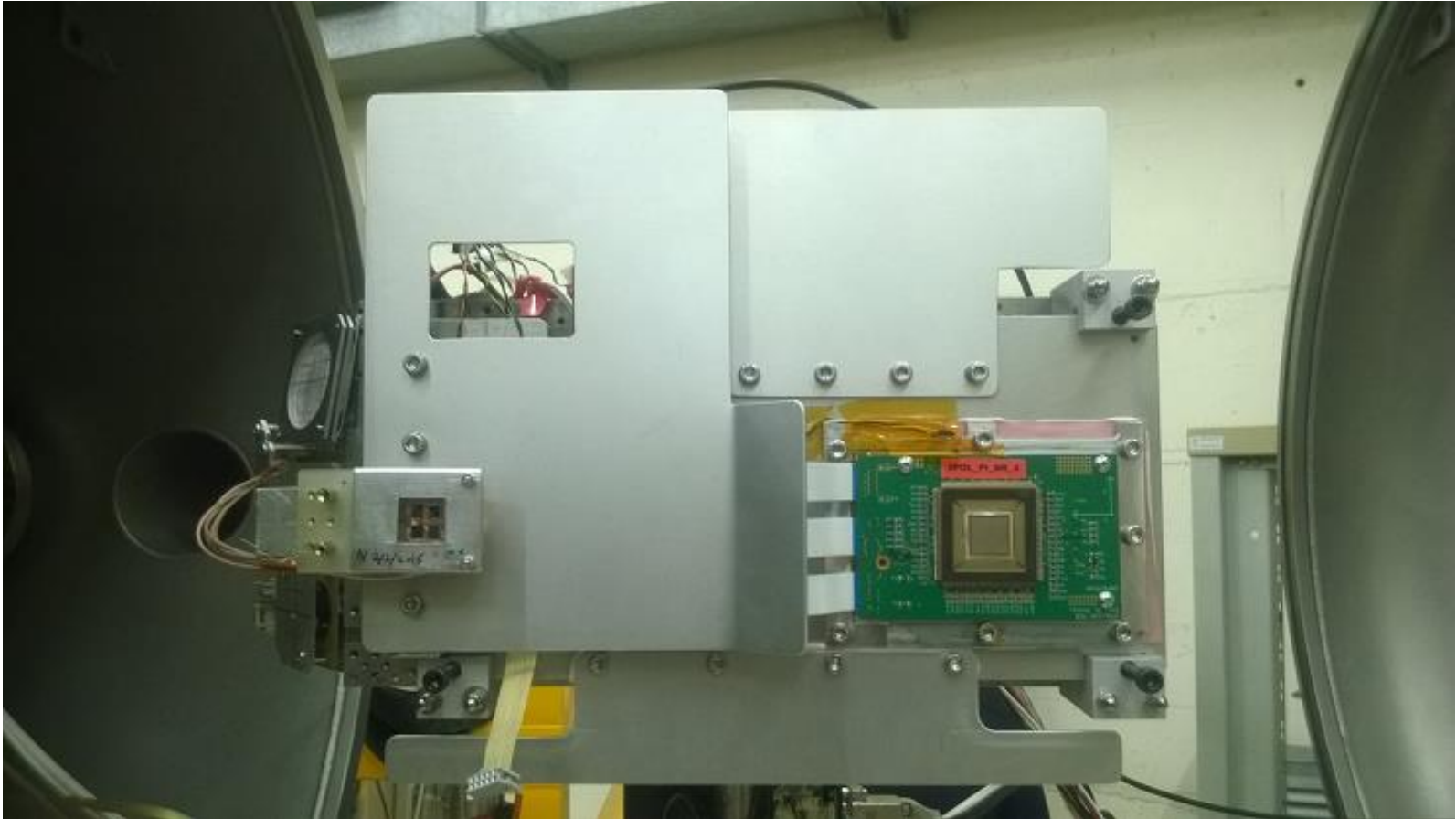
2nd multi-source



Radiation Test: Beam Monitor



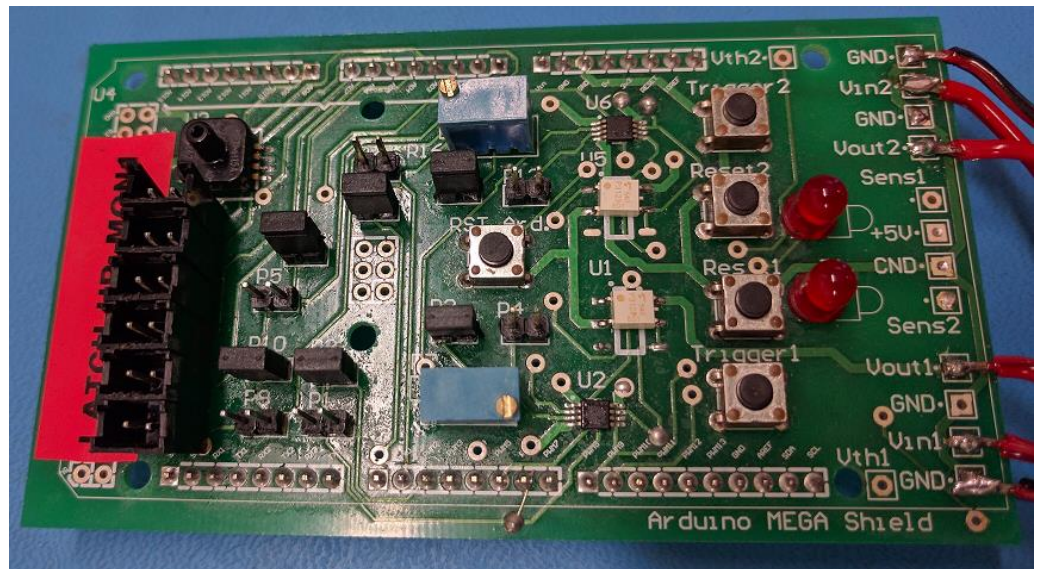
Radiation Test



- ▶ Power dissipation (~ 5 W) is critical in the vacuum chamber

Temperature Sensors

- Six Temperature Sensors on board
 - FPGA
 - ASIC XPOL
 - ADC
 - DC-DC 1.8V
 - DC-DC 3.3V
 - Spare



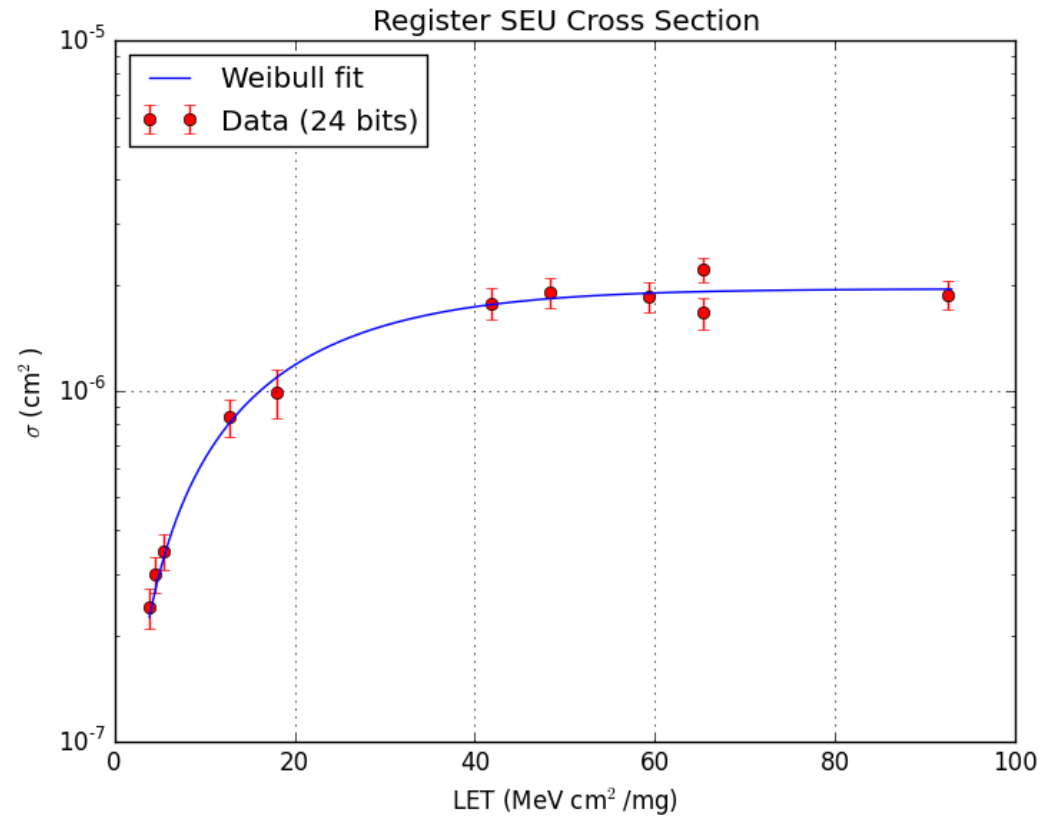
Irradiation Test

- 4 ion species (F, Cl, Br, I) with increasing number mass
- Cumulative dose $\sim 700\text{Krad}$, room for TID effects search in ASIC performance

N. of Runs	24	Tot. Irradiation Time [hrs]	29.90
N. of Configurations	23	Tot. Time Pedestal [hrs]	4.53
N. of SEU Pedestal Tests	11	Tot. Time Registers [hrs]	23.63
N. of SEU Register Tests	12	Nominal* Test time [hrs]	48.00
		*includes installation and beam setup	
Average Flux [ions/(cm² * s)]	4.69E+04	Average Fluence [ions/cm²]	1.15E+08

Results

- Write / Read Memory



Conclusioni

- La progettazione elettronica per lo spazio deve tener conto di:
 - Vuoto, problemi termici
 - Radiazioni Ionizzanti
- Per progettare sistemi che funzionano in questi ambienti bisogna utilizzare componenti elettronici che:
 - Funzionano a temperature in range militare -55°C / $+125^{\circ}\text{C}$
 - Sono immuni o poco suscettibili ai fenomeni: SEU, SEL.
 - Funzionano anche dopo aver ricevuto una dose di radiazione maggiore di quella alla quale verranno esposti.
- Se un componente non ha queste qualifiche bisogna quindi eseguire test di irraggiamento per qualificarlo.



Grazie